

40V, 150A, 3.6mΩ N-channel Power Trench MOSFET

JMTK035N04L

Features

- $\bullet \;\;$ Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED
- 100% ΔVds TESTED
- Halogen-free; RoHS-compliant
- Pb-free plating

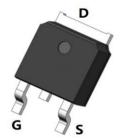
Applications

- Load Switch
- PWM Application
- Power Management

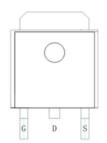
Product Summary

Parameters	Value	Unit
V_{DSS}	40	V
$V_{GS(th)_Typ}$	1.5	V
$I_D(@V_{GS}=10V)$	150	Α
$R_{DS(ON)_Typ}(@V_{GS}=10V$	2.8	mΩ
$R_{DS(ON)_Typ}(@V_{GS}=4.5V$	3.6	mΩ

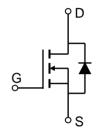




TO-252-3L Top View



Pin Assignment



Schematic Diagram

Ordering Information

Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
JMTK035N04L	JMTK035N04L	3	Tape&Reel	TO-252-3L	2500	25000

Absolute Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{DS}	Drain-to-Source Voltage		40	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	$T_C = 25^{\circ}C$	150	
I _D	Continuous Diain Current	$T_C = 100$ °C	106	A
I_{DM}	Pulsed Drain Current (1)		Refer to Fig.4	Α
E _{AS}	Single Pulsed Avalanche Energ	y ⁽²⁾	316	mJ
P_{D}	Power Dissipation	$T_C = 25^{\circ}C$	115	W
ı D	Fower Dissipation	$T_C = 100$ °C	46	VV
T_{J} , T_{STG}	Junction & Storage Temperature R	lange	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽³⁾	37	°C/W
$R_{\theta,JC}$	Thermal Resistance, Junction to Case	1.1	C/VV



Electrical Characteristics (T_J = 25°C unless otherwise specified)

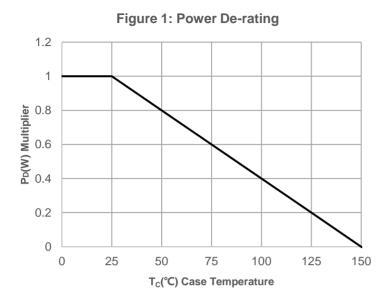
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	racteristics			,		,
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 40V, V_{GS} = 0V$	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Cha	racteristics			•		
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.1	1.5	2.5	V
D	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = 10V, I_D = 30A$	-	2.8 3.8	3.8	mΩ
$R_{DS(ON)}$	Static Drain-Source ON-Resistance	$V_{GS} = 4.5V, I_D = 20A$	-	3.6	5.5	mΩ
Dynami	c Characteristics					
R_{g}	Gate Resistance	f = 1MHz	-	1.3	-	Ω
C _{iss}	Input Capacitance		-	6126	-	pF
C _{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 20V,$ $f = 1MHz$	-	501	-	pF
C _{rss}	Reverse Transfer Capacitance		-	348	-	pF
Q _g	Total Gate Charge	V 0 40V	-	111	-	nC
Q_{gs}	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 20V, I_{D} = 30A$	-	20	-	nC
Q_{gd}	Gate Drain("Miller") Charge	= V _{DS} = 20V, I _D = 30A	-	20	-	nC
					•	
Switchi	ng Characteristics			T	ı	1
$t_{d(on)}$	Turn-On DelayTime		-	14	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 20V$	-	28	-	ns
$t_{d(off)}$	Turn-Off DelayTime	$I_D = 30A, R_{GEN} = 3\Omega$	-	77	-	ns
t _f	Turn-Off Fall Time		-	23	-	ns
Body D	iode Characteristics					
I _S	Maximum Continuous Body Diode Forward	Current	-	-	150	А
I_{SM}	Maximum Pulsed Body Diode Forward Cur	rent	-	-	600	Α
V_{SD}	Body Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 30A$	-		1.2	V
trr	Body Diode Reverse Recovery Time	L = 20A di/dt = 100A/va	-	25	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 30A$, di/dt = 100A/us	-	16.3	-	nC

Notes:

- 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
- $2.~E_{AS}~condition:~Starting~T_J=25C,~V_{DD}=20V,~V_G=20V,~R_G=25ohm,~L=0.5mH,~I_{AS}=35.56A,~V_{DD}=0V~during~time~in~avalanche.$
- 3. $R_{\theta JA}$ is measured with the device mounted on a 1inch $^{\!2}$ pad of 2oz copper FR4 PCB.
- 4. Pulse Test: Pulse Width $\!\!\leqslant\! 300\mu s,$ Duty Cycle $\!\!\leqslant\! 0.5\%.$



Typical Performance Characteristics



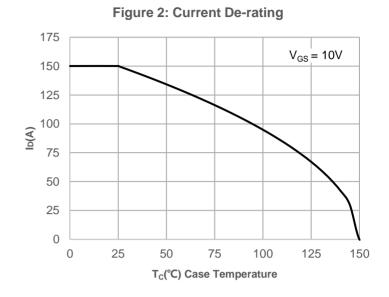
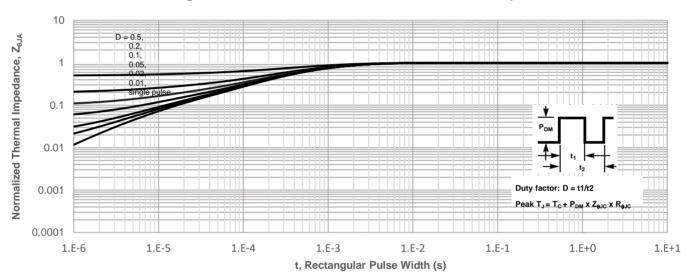
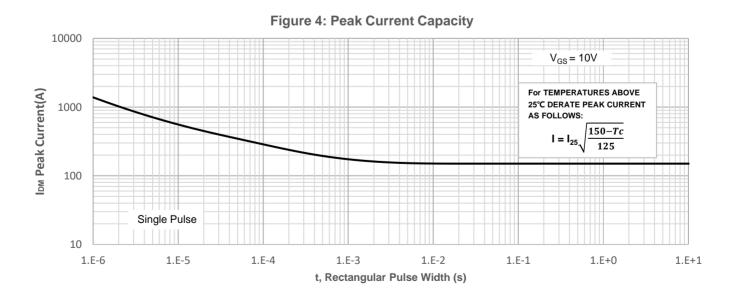


Figure 3: Normalized Maximum Transient Thermal Impedance







Typical Performance Characteristics

Figure 5: Output Characteristics

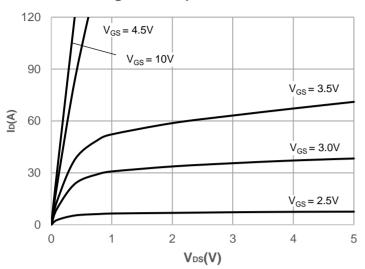


Figure 6: Typical Transfer Characteristics

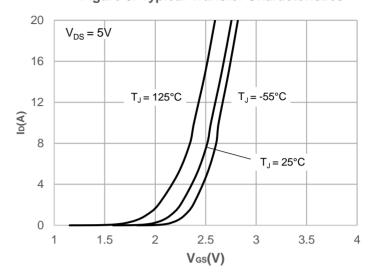


Figure 7: On-resistance vs. Drain Current

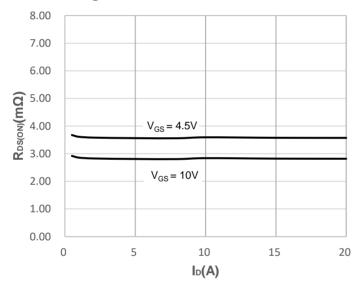


Figure 8: Body Diode Characteristics

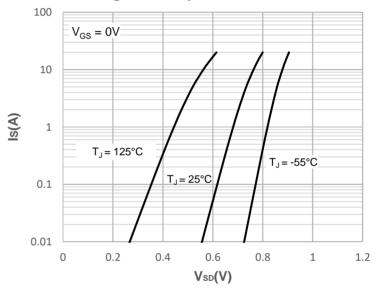


Figure 9: Gate Charge Characteristics

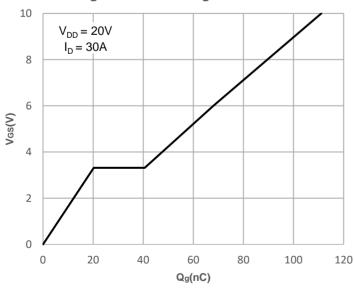
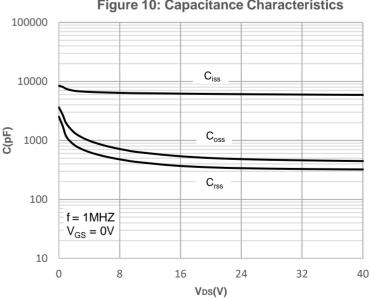


Figure 10: Capacitance Characteristics





Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

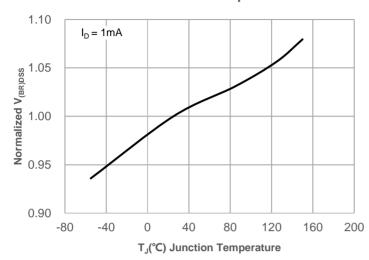


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

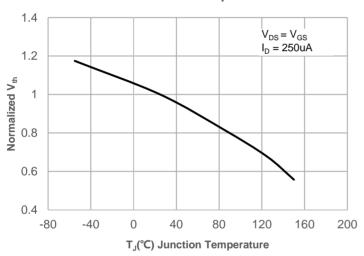


Figure 15: Maximum Safe Operating Area

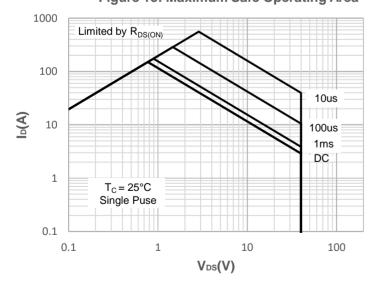
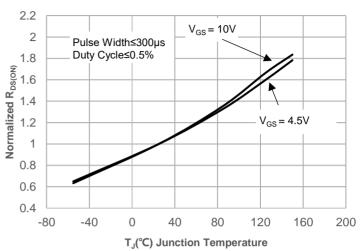
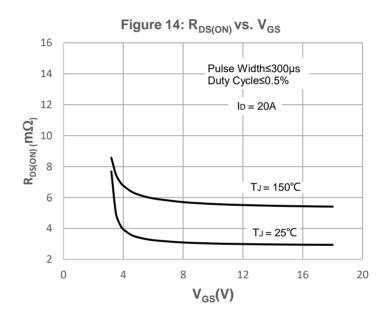


Figure 12: Normalized on Resistance vs. Junction Temperature







Test Circuit

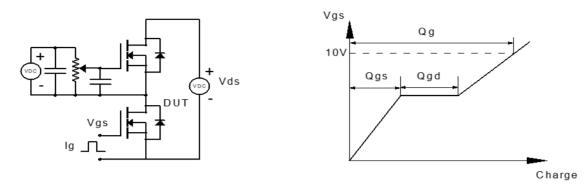


Figure 1: Gate Charge Test Circuit & Waveform

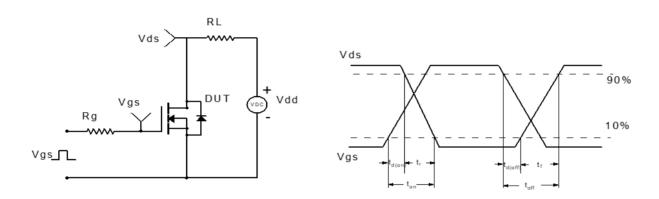


Figure 2: Resistive Switching Test Circuit & Waveform

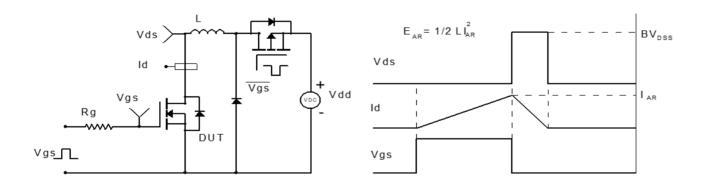


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

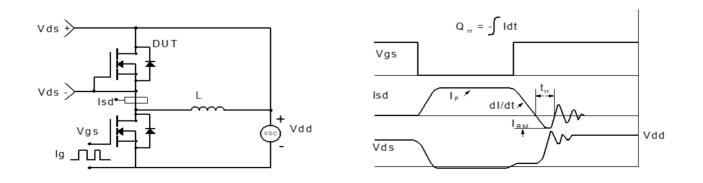
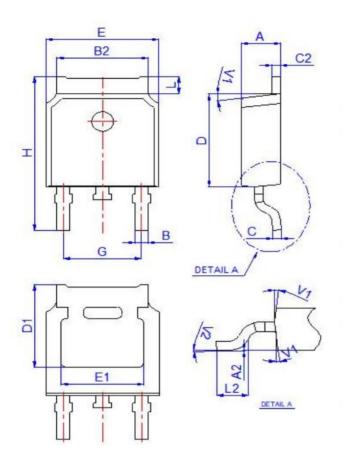


Figure 4: Diode Recovery Test Circuit & Waveform



Package Mechanical Data(TO-252-3L)



Ref.			Dime	ensions			
	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	2.10		2.50	0.083		0.098	
A2	0		0.10	0		0.004	
В	0.66		0.86	0.026		0.034	
B2	5.18		5.48	0.202		0.216	
С	0.40		0.60	0.016		0.024	
C2	0.44		0.58	0.017		0.023	
D	5.90		6.30	0.232		0.248	
D1	5.30REF			(0.209REF		
E	6.40		6.80	0.252		0.268	
E1	4.63			0.182			
G	4.47		4.67	0.176		0.184	
Н	9.50		10.70	0.374		0.421	
L	1.09		1.21	0.043		0.048	
L2	1.35		1.65	0.053		0.065	
V1		7°			7°		
V2	0°		6°	0°	0:	6°	

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